



# GORE™ snapSHOT® Board Level Shield

PCI EXPRESS APPLICATION SUMMARY

## Reduce product size with custom-designed board level shielding

### Application Overview

A customer was developing a new PCI express card for 4G Orthogonal Frequency Division Multiplexing (OFDM) technology. Key issues for this application include the following:

- Low-profile product design
- Co-planarity interference
- Reliable data transmission

The customer originally specified traditional metal cans for shielding; however, once incorporated into the design, they did not meet the height specification for the card.

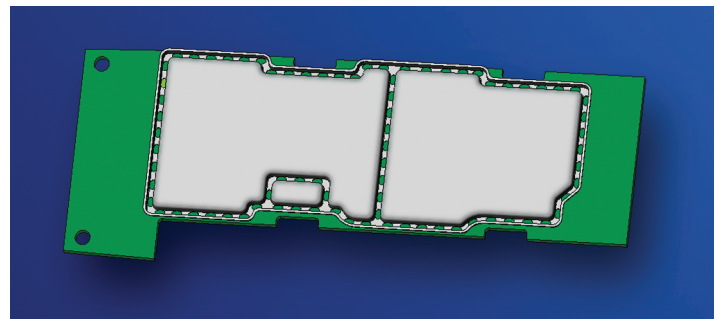
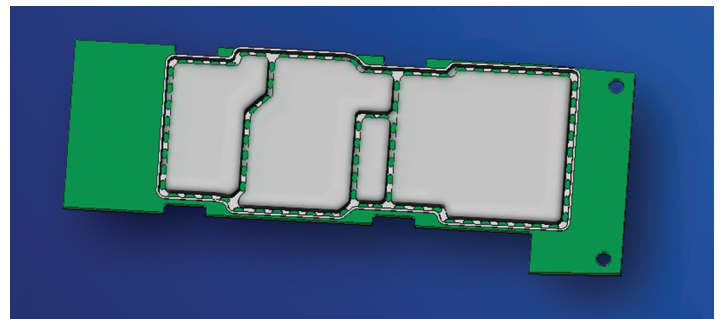
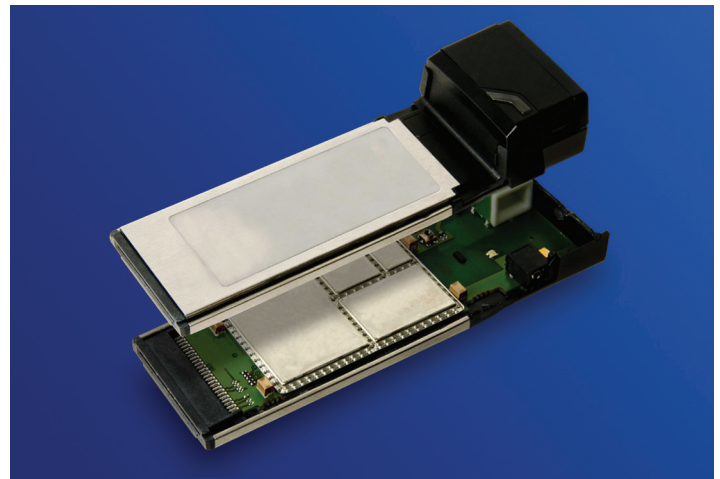
### The Gore Solution

GORE™ snapSHOT® Board-Level Shields are lightweight, multi-cavity shields that allow the customer to reduce product size by varying the height of the shield within each cavity. Using these shields reduced the height of the PCI express card design and eliminated any possible co-planarity issues. At the same time, these shields ensure excellent signal performance up to 12 gigahertz.

### Realize the Benefits of GORE™ snapSHOT® Board-Level Shields

- Reduced product size because of custom-designed shields
- Reliable signal transmission with excellent EMI shielding performance
- Easier implementation with multi-cavity shield design

Drawing on more than 50 years of experience in fluoropolymer research and applications, W. L. Gore and Associates continues to engineer innovative products for board-level shielding. For assistance in selecting the right shielding product for your application, contact your Gore representative today.



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